

# SYNCHRONOUS 16-BIT 1-OF-2 FET MULTIPLEXER/DEMULTIPLEXER

SCDS009K – MAY 1995 – REVISED MAY 2000

- 5-Ω Switch Connection Between Two Ports
- TTL-Compatible Input and Output Levels
- Package Options Include Plastic Thin Shrink Small-Outline (DGG) and Shrink Small-Outline (DL) Packages

## description

The SN74CBT16232 is a synchronous 16-bit 1-of-2 FET multiplexer/demultiplexer used in applications in which two separate data paths must be multiplexed onto, or demultiplexed from, a single path.

Two select (S0 and S1) inputs control the data flow. A clock (CLK) and a clock enable ( $\overline{\text{CLKEN}}$ ) synchronize the device operation. When  $\overline{\text{CLKEN}}$  is high, the bus switch remains in the last clocked function.

The SN74CBT16232 is characterized for operation from -40°C to 85°C.

## DGG OR DL PACKAGE (TOP VIEW)

1A	1	56	1B1
2B1	2	55	1B2
2B2	3	54	2A
3A	4	53	3B1
4B1	5	52	3B2
4B2	6	51	4A
5A	7	50	5B1
6B1	8	49	5B2
6B2	9	48	6A
7A	10	47	7B1
8B1	11	46	7B2
8B2	12	45	8A
GND	13	44	GND
V <sub>CC</sub>	14	43	V <sub>CC</sub>
9A	15	42	9B1
10B1	16	41	9B2
10B2	17	40	10A
11A	18	39	11B1
12B1	19	38	11B2
12B2	20	37	12A
13A	21	36	13B1
14B1	22	35	13B2
14B2	23	34	14A
15A	24	33	15B1
16B1	25	32	15B2
16B2	26	31	16A
CLK	27	30	S0
$\overline{\text{CLKEN}}$	28	29	S1

FUNCTION TABLE

INPUTS				FUNCTION
S1	S0	CLK	$\overline{\text{CLKEN}}$	
X	X	X	H	Last state
L	L	↑	L	Disconnect
L	H	↑	L	A = B1 and A = B2
H	L	↑	L	A = B1
H	H	↑	L	A = B2

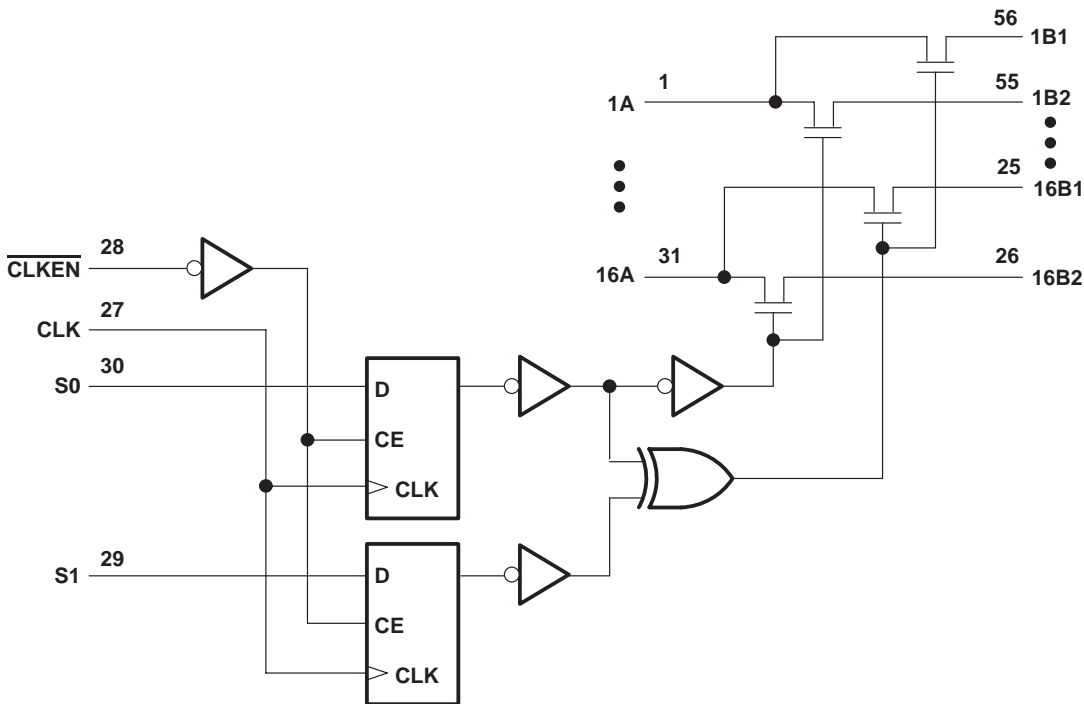
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## logic diagram (positive logic)



## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, $V_{CC}$ .....	-0.5 V to 7 V
Input voltage range, $V_I$ (see Note 1) .....	-0.5 V to 7 V
Continuous channel current .....	128 mA
Input clamp current, $I_{IK}$ ( $V_I < 0$ ) .....	-50 mA
Package thermal impedance, $\theta_{JA}$ (see Note 2): DGG package .....	64°C/W
DL package .....	56°C/W
Storage temperature range, $T_{stg}$ .....	-65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.  
2. The package thermal impedance is calculated in accordance with JESD 51.

## recommended operating conditions (see Note 3)

		MIN	MAX	UNIT
$V_{CC}$	Supply voltage	4	5.5	V
$V_{IH}$	High-level control input voltage	2		V
$V_{IL}$	Low-level control input voltage		0.8	V
$T_A$	Operating free-air temperature	-40	85	°C

NOTE 3: All unused control inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

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**electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)**

PARAMETER		TEST CONDITIONS		MIN	TYP†	MAX	UNIT	
$V_{IK}$		$V_{CC} = 4.5\text{ V}$ , $I_I = -18\text{ mA}$				-1.2	V	
$I_I$		$V_{CC} = 5.5\text{ V}$ , $V_I = 5.5\text{ V}$ or GND				$\pm 1$	$\mu\text{A}$	
$I_{CC}$		$V_{CC} = 5.5\text{ V}$ , $I_O = 0$ , $V_I = V_{CC}$ or GND				3	$\mu\text{A}$	
$\Delta I_{CC}^\ddagger$	Control inputs	$V_{CC} = 5.5\text{ V}$ , One input at 3.4 V, Other inputs at $V_{CC}$ or GND				2.5	mA	
$C_i$	Control inputs	$V_I = 3\text{ V}$ or 0				4.5	pF	
$C_{io}(\text{OFF})$	A port	$V_O = 3\text{ V}$ or 0, $\overline{\text{CLKEN}} = 0$ , $S0 = 0$ , $S1 = 0$				6.5	pF	
	B port					4		
$r_{on}^\S$	$V_{CC} = 4\text{ V}$ , TYP at $V_{CC} = 4\text{ V}$	$V_I = 2.4\text{ V}$ ,	$I_I = 15\text{ mA}$			14	20	$\Omega$
			$V_{CC} = 4.5\text{ V}$	$V_I = 0$	$I_I = 64\text{ mA}$			
	$I_I = 30\text{ mA}$					5	7	
		$V_I = 2.4\text{ V}$ ,	$I_I = 15\text{ mA}$			10	15	

† All typical values are at  $V_{CC} = 5\text{ V}$  (unless otherwise noted),  $T_A = 25^\circ\text{C}$ .

‡ This is the increase in supply current for each input that is at the specified TTL voltage level rather than  $V_{CC}$  or GND.

§ Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

**timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)**

PARAMETER			$V_{CC} = 4\text{ V}$		$V_{CC} = 5\text{ V} \pm 0.5\text{ V}$		UNIT
			MIN	MAX	MIN	MAX	
$f_{\text{clock}}$	Clock frequency		150		150		MHz
$t_w$	Pulse duration		3.3		3.3		ns
$t_{su}$	Setup time	$S0, S1$ before $\text{CLK}\uparrow$	2.2		1.9		ns
		$\overline{\text{CLKEN}}$ before $\text{CLK}\uparrow$	2.4		1.9		
$t_h$	Hold time	$S0, S1$ after $\text{CLK}\uparrow$	0.5		1		ns
		$\overline{\text{CLKEN}}$ after $\text{CLK}\uparrow$	1.9		1.8		

**switching characteristics over recommended operating free-air temperature range,  $C_L = 50\text{ pF}$  (unless otherwise noted) (see Figure 1)**

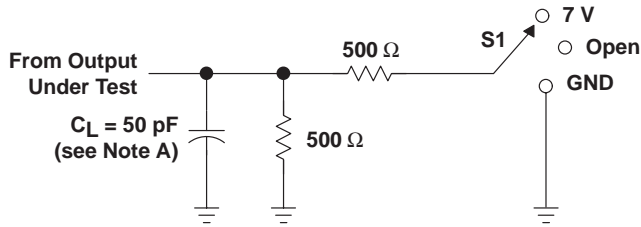
PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 4\text{ V}$		$V_{CC} = 5\text{ V} \pm 0.5\text{ V}$		UNIT
			MIN	MAX	MIN	MAX	
$f_{\text{max}}$			150		150		MHz
$t_{pd}^{\parallel}$	A or B	B or A	0.35		0.25		ns
$t_{pd}$	CLK	A or B	6.1		2	5.8	ns
$t_{en}$	CLK	A, B1, B2	6.8		1.8	6.2	ns
		B1 and B2	8.5		3.1	7.9	
$t_{dis}$	CLK	A or B	5.8		1.9	6.2	ns

$\parallel$  The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

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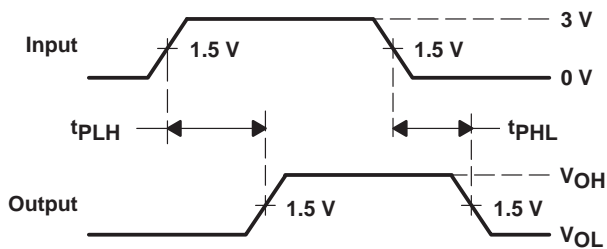
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## PARAMETER MEASUREMENT INFORMATION

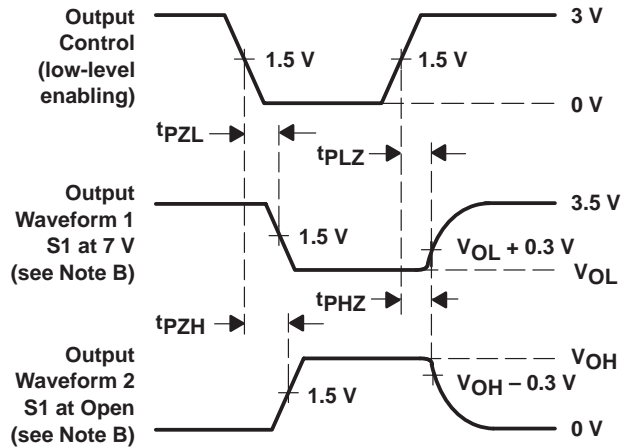


LOAD CIRCUIT

TEST	S1
$t_{pd}$	Open
$t_{PLZ}/t_{PZL}$	7 V
$t_{PHZ}/t_{PZH}$	Open



VOLTAGE WAVEFORMS  
PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS  
ENABLE AND DISABLE TIMES

- NOTES:
- $C_L$  includes probe and jig capacitance.
  - Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
  - All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10 \text{ MHz}$ ,  $Z_O = 50 \Omega$ ,  $t_r \leq 2.5 \text{ ns}$ ,  $t_f \leq 2.5 \text{ ns}$ .
  - The outputs are measured one at a time with one transition per measurement.
  - $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
  - $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
  - $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .

Figure 1. Load Circuit and Voltage Waveforms

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